



PK1211(v1.0) December 9, 2024

100% Material Declaration Data Sheet for XQ Grade XQ7Z020-CL484

Average Weight : 1.2860 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die					0.025878	2.012%
	Silicon	7440-21-3	100.00	Basis	0.025878	
Die Attach Material	Silver	7440-22-4	80.50	Metal	0.008250	0.642%
	Bismaleimide monomer	trade secret	7.50		0.006641	
	2-[[2,2-bis[[1-(oxoallyloxy)methyl]butoxy]methyl]-2-ethyl-1,3-propanediyl diacrylate	94108-97-1	3.00		0.000248	
	A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol; 4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2,6-bis(2,3-epoxypropyl)phenoxy)-2-hydroxypropyl]-4-allyl-2-(2,3-epoxypropyl)phenoxy]-2-hydroxypropyl]-4-allyl-2-(2,3-epoxypropyl)phenoxy]-2-hydroxypropyl]-2-(2,3-epoxypropyl)phenol; 4-allyl-6-[3-[6-[3-(4-allyl-2,6-bis(2,3-epoxypropyl)phenoxy)-2-hydroxypropyl]-4-allyl-2-(2,3-epoxypropyl)phenoxy]-2-hydroxypropyl]-2-(2,3-epoxypropyl)phenol; 4-allyl-6-[3-[6-[3-(4-allyl-2,6-bis(2,3-epoxypropyl)phenoxy)-2-hydroxypropyl]-4-allyl-2-(2,3-epoxypropyl)phenoxy]-2-hydroxypropyl]-2-(2,3-epoxypropyl)phenol	trade secret	3.00		0.000248	
	Carbamate resin	trade secret	3.00		0.000248	
	Neopentyl glycol propoxylate diacrylate	84170-74-1	3.00		0.000248	
						0.006315
Copper Wire	Copper	7440-50-8	98.08	Metal	0.006194	
	Palladium	7440-05-3	1.80	Metal	0.000114	
	Gold	7440-57-5	0.12	Metal	0.000008	
					0.476918	37.085%
Mold Compound	2,2'-((3,3',5,5'-tetramethyl-(1,1'-biphenyl)-4,4'-diyl)-bis(oxymethylene))-bis-oxirane	85954-11-6	7.50	Basis	0.035769	
	Phenol Resin A	9003-35-4	3.00	Basis	0.014308	
	Phenol Resin B	trade secret	3.00	Basis	0.014308	
	Silica(Amorphous) A	60676-86-0	67.95	Additives	0.324066	
	Silica(Amorphous) B	7631-86-9	15.00		0.071538	
	Metal Hydroxide	trade secret	3.00	Filler	0.014308	
	Carbon black	1333-86-4	0.55	Glue	0.002623	
					0.266591	20.730%
Solder Ball	Tin	7440-31-5	63.00	Main Material	0.167952	
	Lead	7439-92-1	37.00	Main Material	0.098639	
					0.502048	39.040%
Substrate	Gold	7440-57-5	0.23	Metal	0.001175	
	Nickel	7440-02-0	2.16	Metal	0.010836	
	Cu foil	7440-50-8	14.98	Metal	0.075210	
	Cu plating	7440-50-8	8.74	Metal	0.043872	
	Continuous Filament Fiber Glass	65997-17-3	24.53		0.123172	
	BT Core	NA/7440-50-8	33.71		0.169236	
	Solder mask	7727-43-7/7631-86-9 34590-94-8/14807-96-6 85954-11-6/91-20-3/NA	7.39	Solder Mask	0.037125	
PP	NA	8.25		0.041421		

Revision History

Date	Version	Description of Revisions
12/9/2024	1.0	Initial AMD Release.

Notice of Disclaimer

AMD regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. AMD subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. AMD has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of AMD products.